ASSOCIATION CONNECTING	© Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docum level parts,	ent is a declara the declaration	tion of the s encompass	ubstances es all lower	within the manufactur r level materials for w	rer listed in hich the m	em. Note: it anufacturer	f the item is an as has engineering	sembly with lower responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials a					s and Mfg Information			
Supplier Inform	ation													
Company name*			Company unique ID			Unique ID Authority				Response Date*				
onsemi											2025-05-13			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative				Phone - Representative*				Email - Representative*			
Product-Env-Stewa	rds	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Dat	Date Version Manufacturing Site			Weight*	UOM	Unit Type	
		FSB5045	SB50450BS SPM5 V		PM5 V3 INV 500V 3.80hm		2025-05-13		C	СРА		3355.2	mg	Each
Manufacturing l	Proccess Information	1												
Terminal Plating / Grid Array Material Term			erminal Base A	minal Base Alloy J-STD-020 MSL R		L Rating	Peak Process Body Temperature		ure Max Time at Peak Tempera		ure Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Al			U Alloy	loy 3			260 C 30			seconds 3				
Comments														
TTENTION: MSL	3 Rated item requires Ba	ke and D	ry Pack (after	electrical test)										
or more informatio	on regarding material con	position j	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
	all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the a Submit Form to have the form returned to the Requester.									
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	24.0	mg	Supplier	Silicon (Si)	7440-21-3		24	mg
Die Attach	6.0	mg	Supplier	Silver (Ag)	7440-22-4		4.56	mg
			Supplier	Phenolic Resin-2	54208-63-8		1.44	mg
Die Attach Solder	4.8	mg	Supplier	Silver (Ag)	7440-22-4		0.12	mg
			А	Lead (Pb)	7439-92-1	7a	4.44	mg
			Supplier	Tin (Sn)	7440-31-5		0.24	mg
Lead Frame	1370.0	mg	Supplier	Silver (Ag)	7440-22-4		20.002	mg
			В	Nickel (Ni)	7440-02-0		30.003	mg
			Supplier	Iron (Fe)	7439-89-6		1.37	mg
			Supplier	Copper (Cu)	7440-50-8		1318.214	mg
			Supplier	Phosphorus (P)	7723-14-0		0.411	mg
Mold Compound-Black	1890.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		132.3	mg
			Supplier	Carbon Black (C)	1333-86-4		18.9	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		661.5	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		132.3	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		945	mg
Plating	56.4	mg	Supplier	Tin (Sn)	7440-31-5		56.4	mg
Wire Bond - Cu	4.0	mg	Supplier	Palladium (Pd)	7440-05-3		0.08	mg
			Supplier	Copper (Cu)	7440-50-8		3.92	mg